



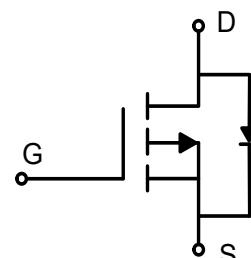
Shenzhen Tuofeng Semiconductor Technology Co., Ltd

P -CHANNEL ENHANCEMENT MODE POWER MOSFET**TF350P04K****Description**

TF350P04K uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

**Features**

- $V_{DS} = -40V$, $I_D = -24A$
 $R_{DS(on)} = 32m\Omega$ Typ@ $V_{GS} = -10V$
 $R_{DS(on)} = 42m\Omega$ Typ@ $V_{GS} = -4.5V$
- Extremely Low Switching Loss
- Excellent Stability and Uniformity
- Low Gate Charge
- 100% EAS Guaranteed

**Applications**

- Power Management Switches
- DC/DC Converter

Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current <small>$T_C = 25^\circ C$</small>	I_D	-24	A
		-15	
Pulsed Drain Current ¹	I_{DM}	-76	A
Single Pulse Avalanche Energy ²	EAS	55	mJ
Total Power Dissipation <small>$T_C = 25^\circ C$</small>	P_D	20	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	73	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	17	°C/W



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Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J = 25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	μA
$T_J = 100^\circ\text{C}$			-	-	-100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.7	-2.5	V
Drain-Source On-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -8.0\text{A}$	-	32	40	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -5.0\text{A}$		42	55	
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_D = -10.0\text{A}$	-	15	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	1021	-	pF
Output Capacitance	C_{oss}		-	63.6	-	
Reverse Transfer Capacitance	C_{rss}		-	48.6	-	
Gate Resistance	R_g	$f = 1\text{MHz}$	-	4.7	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = -10\text{V}, V_{\text{DS}} = -20\text{V}, I_D = -10\text{A}$	-	19.3	-	nC
Gate-Source Charge	Q_{gs}		-	2.5	-	
Gate-Drain Charge	Q_{gd}		-	5.5	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, V_{\text{DD}} = -20\text{V}, R_G = 2.5\Omega, I_D = -10\text{A}$	-	13.0	-	ns
Rise Time	t_r		-	16.0	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	180	-	
Fall Time	t_f		-	86.0	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -5.0\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	29	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	20	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = -10\text{A}, V_{\text{GS}} = 0\text{V}$	-	0.85	-1.2	V
Continuous Source Current	$T_C = 25^\circ\text{C}$	I_S	-	-	-10	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}= -20\text{V}, V_{\text{GS}}= -10\text{V}, L= 0.5\text{mH}, I_{\text{AS}}= -10\text{A}$
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test..

Typical Electrical And Thermal Characteristics (Curves)

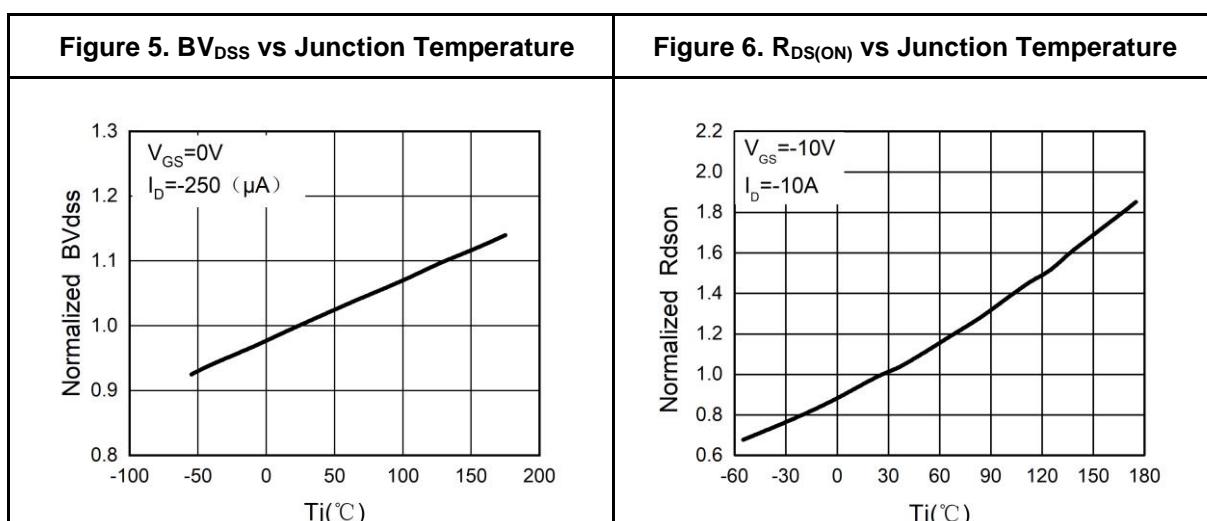
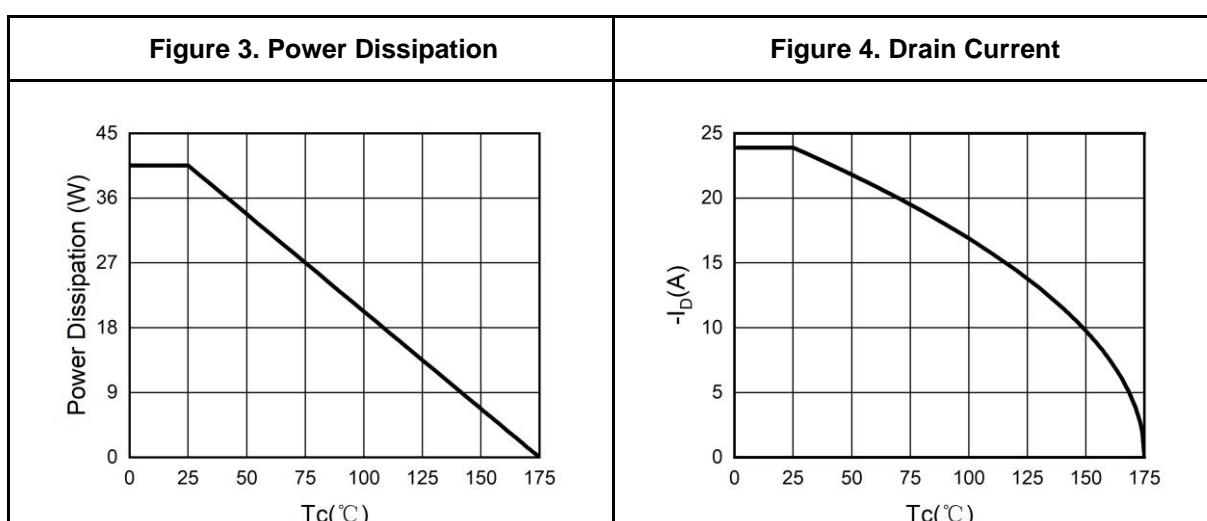
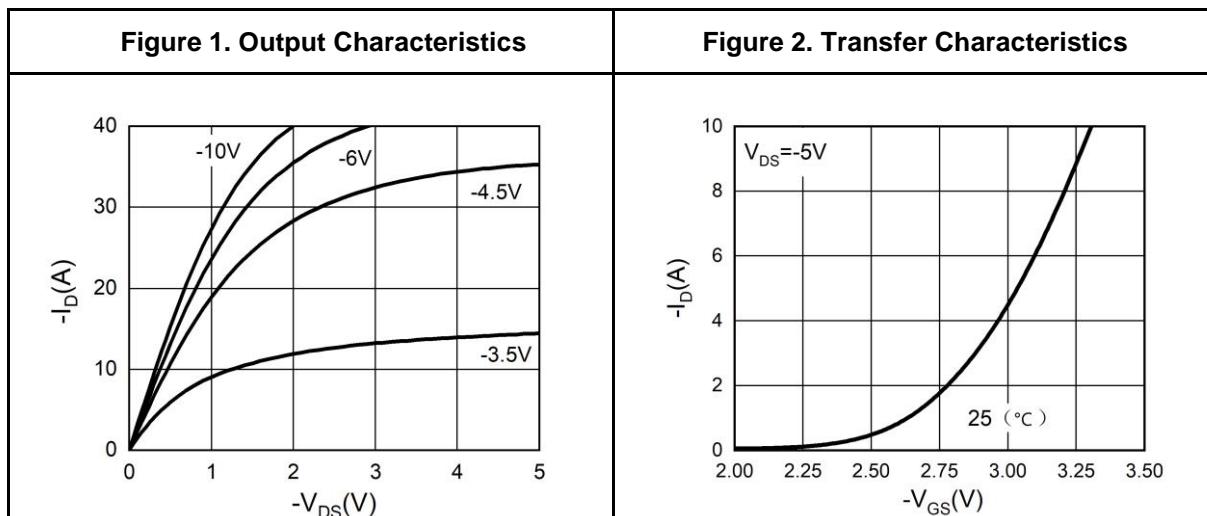


Figure 7. Gate Charge Waveforms

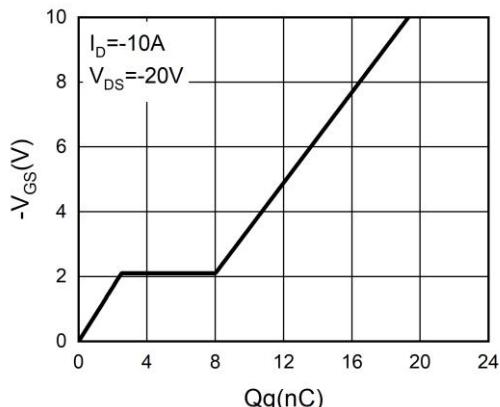


Figure 8. Capacitance

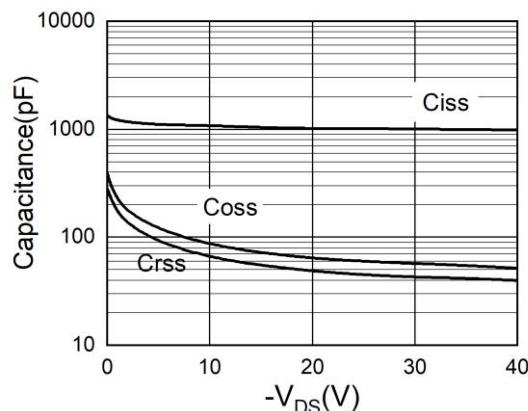


Figure 9. Body-Diode Characteristics

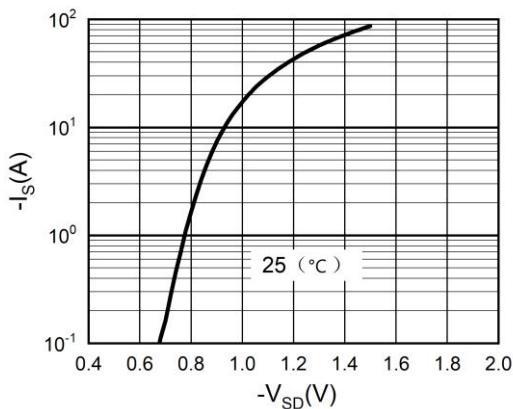
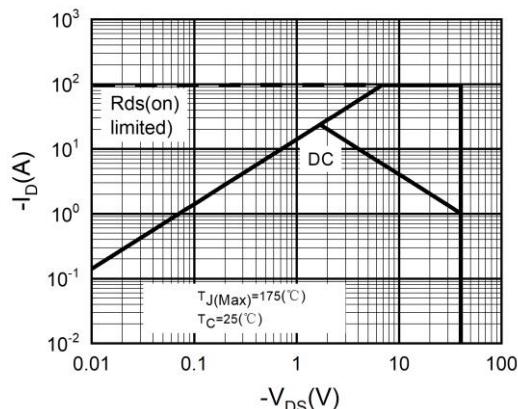


Figure 10. Maximum Safe Operating Area



Test Circuit

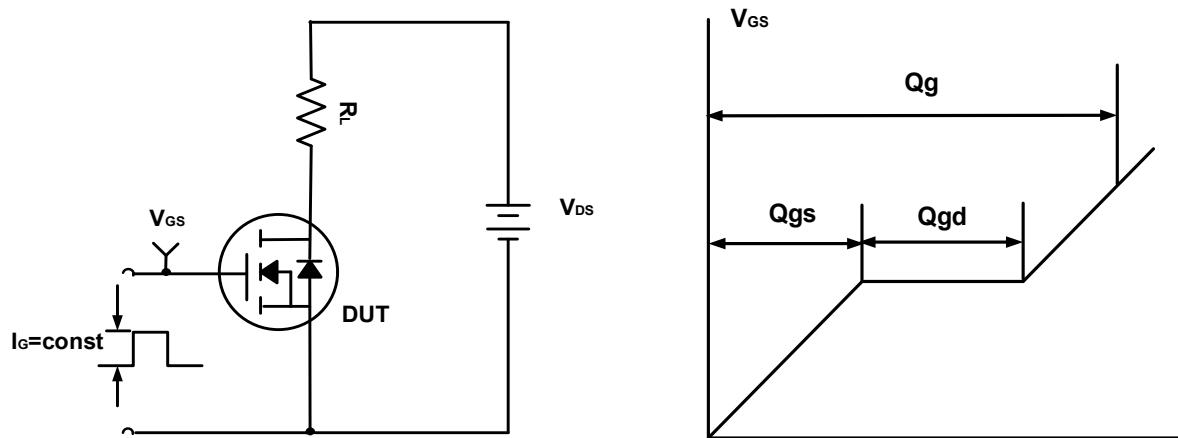


Figure A. Gate Charge Test Circuit & Waveforms

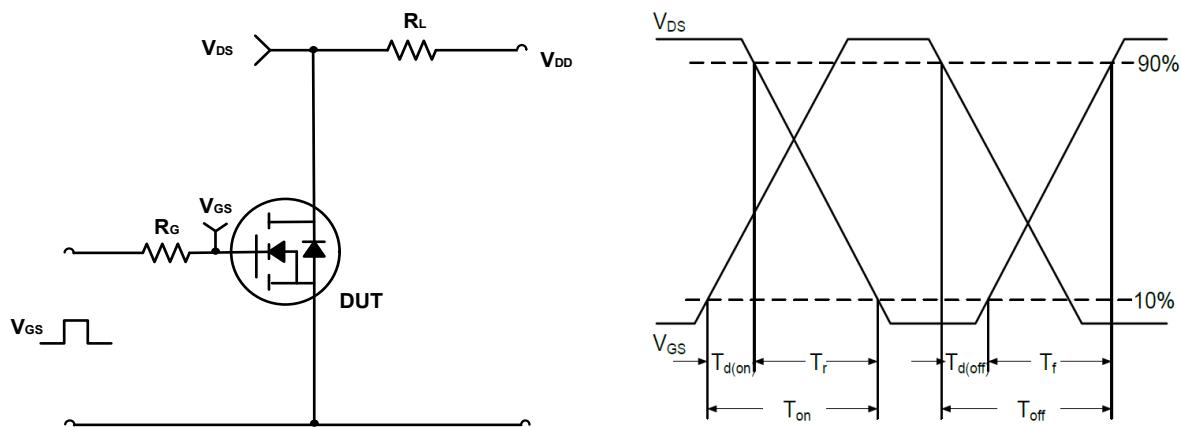


Figure B. Switching Test Circuit & Waveforms

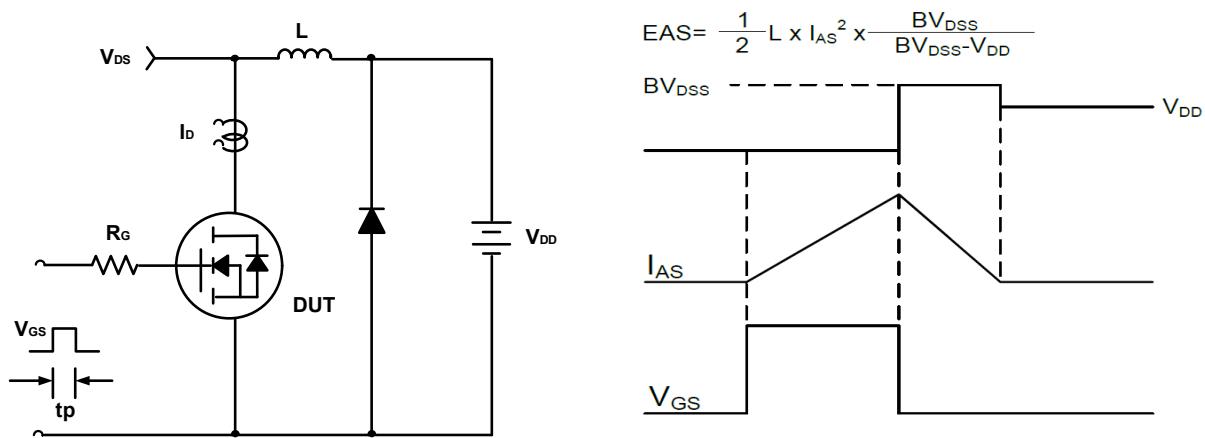


Figure C. Unclamped Inductive Switching Circuit & Waveforms



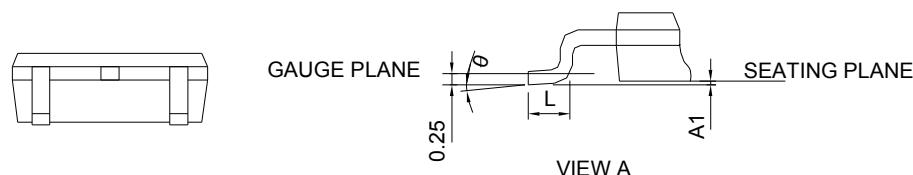
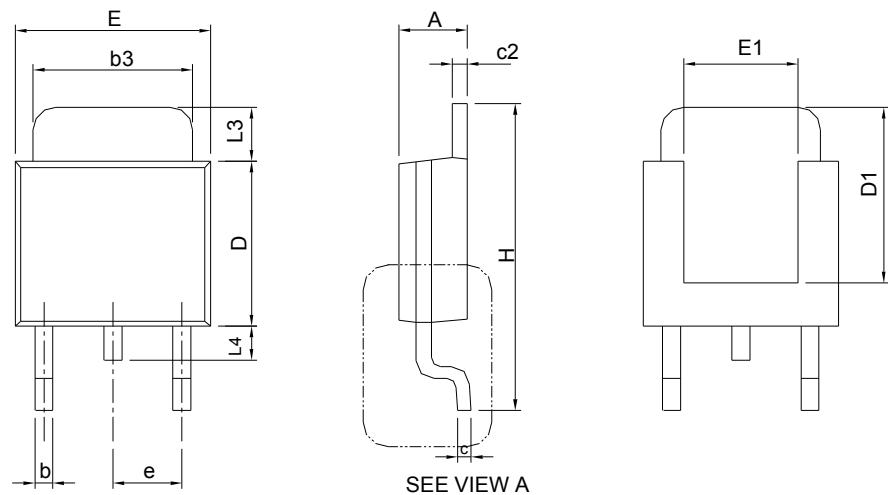
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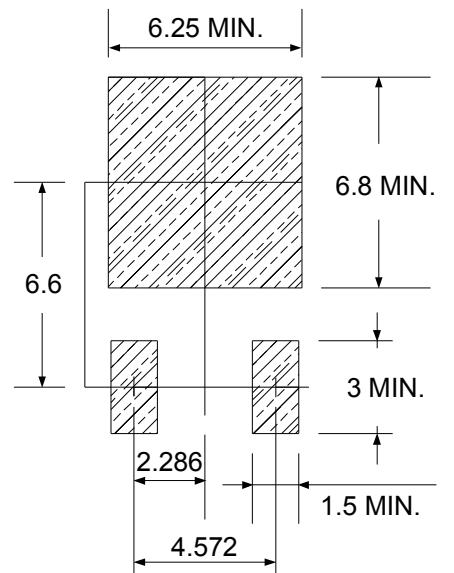
Package Information

TO-252



SYMBOL	TO-252			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

RECOMMENDED LAND PATTERN



UNIT: mm